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## PAPERS OVERVIEW

### TOPIC A – EMERGING TECHNOLOGIES & TRENDS IN ADVANCED PACKAGING

[PP. 25-30.:](#)

SENSING PROPERTIES OF CARBON NANOTUBE BASED THICK FILM LAYERS ON FOILS

Detlef Bonfert, Dieter Hemmetzberger, Gerhard Klink, Karlheinz Bock, Paul Svasta, Ciprian Ionescu

[PP. 31-34.:](#)

INVESTIGATION OF THERMALLY GENERATED GOLD NANOPARTICLES WITH AFM

Attila Bonyár, Balázs Wimmer, István Csarnovics

[PP. 35-38.:](#)

HARDWARE IMPLEMENTATION OF THE IDEA NXT CRYPTO-ALGORITHM

Andreea Bozesan, Flavius Opritoiu, Mircea Vladutiu

[PP. 39-42.:](#)

SOLDERING TESTS WITH BIODEGRADABLE PRINTED CIRCUIT BOARDS

A. Geczy, T. Garami, B. Kovacs., D. Nagy, L. Gal, M. Ruzinko, I. Hajdu

[PP. 43-47.:](#)

POLYMER MATRIX COMPOSITES REINFORCED WITH EXPANDED AND UNEXPENDED GRAPHITE  
PARTICLES FOR ELECTRONIC PACKAGING APPLICATIONS

Ismail Tavman, Alpaslan Turgut, Nicolas Horny, Mihai Chirtoc

### TOPIC B – POWER ELECTRONICS AND MICROSYSTEMS PACKAGING

[PP. 51-56.:](#)

OPTIMAL MICROHEATER PATTERNS WITH PEDOT:PSS CONDUCTORS FOR FLEXIBLE SENSOR  
APPLICATIONS

C. Ionescu, N.D. Codreanu, P. Svasta, D. Bonfert

### TOPIC C – ASSEMBLY AND MANUFACTURING TECHNOLOGY

[PP. 59-64.:](#)

INVESTIGATING HOLE FILLING IN PIN-IN-PASTE TECHNOLOGY FOR VAPOUR PHASE SOLDERING

Reka Batorfi, Richard Storcz, Miklos Ruzinko

[PP. 65-68.:](#)

REDUCING LEAD-FREE SOLDERING FAILURES CAUSED BY PRINTED CIRCUIT BOARD SHRINKAGE

A. Geczy, L. Tersztyanszky, B. Illes, A. Kemler, A. Szabo

[PP. 69-74.:](#)

MODELING GALDEN LAYER FORMATION ON PCB SURFACE DURING VAPOUR PHASE SOLDERING

Balázs Illés

[PP. 75-78.:](#)

NEW METHOD FOR CALCULATING THE NECESSARY AMOUNT OF SOLDER PASTE FOR PIN-IN-PASTE TECHNOLOGY

Oliver Krammer

[PP. 79-82.:](#)

INFLUENCE OF FILLER CONCENTRATION ON FREQUENCY DEPENDENCE OF ELECTRICALLY CONDUCTIVE ADHESIVE JOINTS IMPEDANCE

Pavel Mach, Martin Plaček

#### **TOPIC D – DESIGN OF ELECTRONIC CIRCUITS AND SYSTEMS**

[PP. 85-88.:](#)

A VLSI IMPLEMENTATION OF THE 4TH ORDER ELLIPTIC FULLY DIFFERENTIAL IIR SWITCHED-CAPACITOR LOW-PASS FILTER IN CMOS TECHNOLOGY

Radu Gabriel Bozomitu, Neculai Cojan, Gabriel Bonteanu

[PP. 89-94.:](#)

A NEW FORWARD BASED CONVERTER WITH POWER FACTOR CORRECTION

C. Fărcaș, N. Palaghîță, I. Ciocan, A. Cozma, A. Tulbure

[PP. 95-98.:](#)

LOW-COST PICOAMMETER FOR DIELECTRICS

S. Epure, R. Belea, L. Frangu

[PP. 99-102.:](#)

LONG RANGE IMAGE RADIO TRANSMITTER

Andrei Hapenciuc, Paul Svasta

[PP. 103-106.:](#)

WIRELESS CONTROL SYSTEM FOR ANGULAR POSITIONING APPLICATIONS

Daniel Alexandru Visan, Ioan Lita, Ion Bogdan Cioc

[PP. 107-112.:](#)

COMPARATIVE ANALYSIS OF TWO DIGITAL CONTROL ALGORITHMS FOR A DC-DC CONVERTER

C. Orian, D. Petreuş, R. Etz, T. Pătărău

[PP. 113-116.:](#)

STUDY AND IMPLEMENTATION OF A VAPORIZER USED IN PLASMA EQUIPMENT FOR HEAVY METALS DETECTION

T. Patarau, D. Petreus, R. Etz, C. Orian, E. Darvasi, T. Frentiu

[PP. 117-122.:](#)

ASPECTS OF DATA RECEPTION IN A HIGH PERFORMANCE RFID READER

Dan Tudor Vuza, Reinhold Frosch, Helmut Koeberl

## **TOPIC E – ELECTRONICS SIMULATION & MODELLING**

[PP. 125-128.:](#)

PCB LAYOUT OPTIMIZATION FOR LED BACKLIGHT MODULE USING FEM SIMULATION

Aurelian Botau, Catalin Negrea

[PP. 129-133.:](#)

MODELS OF DIELECTRIC MATERIALS USED IN HIGH-SPEED DESIGN BY FD2TD METHOD

D. Bucur, N. Militaru, G. Lojewski

[PP. 135-138.:](#)

PROGRESSIVE TRANSMISSION LINE MATCHING WHEN ENCOUNTERING VIA MISMATCHING

Mihai Daraban, Dan Pítica

[PP. 139-143.:](#)

ADAPTIVE NOISE CANCELLATION USING LABVIEW

C. I. Dumitrescu, I.M. Moise, B. Soare, N. Dumitru

## **TOPIC**

THE EFFECT OF CAVITY LENGTH ON THE COOLING OF THE HIGH POWER SEMICONDUCTOR DIODE LASER

E. Farsad, S. P. Abbasi, M. S. Zabihi

[PP. 149-152.:](#)

THERMAL MODELLING OF IC PACKAGES

Alexandra Fodor, Rajmond János

[PP. 153-157.:](#)

THE EXPERIMENTAL STAND FOR THE STUDY OF THE HYDRO WIND HYBRID POWER STATIONS

R. Joian, D. Petreuş, R. Etz, C. Lung

[PP. 159-162.:](#)

SIMULATOR FOR SIGNALS FROM SEMICONDUCTOR RADIATION SENSORS USED IN TESTING OF RADIATION MEASUREMENT APPARATUS

Ion Bogdan Cioc, Ioan Lita, Daniel Alexandru Visan

[P IC](#)

A NUMERICAL STUDY ON THE THERMAL MANAGEMENT OF A LED ARRAY

Ömer Mermer, Metin Nil, M. Bahattin Akgul

[PP. 167-170.:](#)

MODELING AND SIMULATION OF INDUCTIVE STRUCTURES FOR NON-INVASIVE MEDICAL USES

B. Mihailescu, I. Plotog, P. Svasta, C. Marghescu

[PP. 171-176.:](#)

DATA IMPROVEMENT IN LAB VERIFICATION OF SMART POWER PRODUCTS USING DOE

Anamaria Oros, Ingrid Kovacs, Marina Topa, Andi Buzo, Monica Rafaila, Manuel Harrant, Georg Pelz

[PP. 177-180.:](#)

DIFFERENTIAL POWER ANALYSIS: SIMULATED VERSUS EXPERIMENTAL ATTACKS

Ciprian Leonard Piţu, Ciprian Leonard Piţu, Radu Câmpeanu

[PP. 181-184.:](#)

TWO PARAMETER EXTRACTION SOLUTIONS FOR HIGH TEMPERATURE SIC SCHOTTKY DIODES – CONVERGING TO REALITY

Gh. Pristavu, Gh. Brezeanu, F. Draghici

[PP. 185-189.:](#)

HIGH-LOW IMPEDANCE TRANSFORMER USING TRANSMISSION LINE METHOD

Ruei-Ying Fang, Chia-Fen Liu, Chieh-Yu Liao, Chun-Long Wang

## **TOPIC F – ELECTRONICS APPLICATIONS**

[PP. 193-196.:](#)

COMPARATIVE ANALYSIS OF THE MEASUREMENT METHODS FOR THE WIRE'S POSITION USING THE TSL1410R OPTICAL SENSOR

V. Bande, S. Pop, D. Pitica

[PP. 197-200.:](#)

SHUNT LESS CURRENT MONITORING TECHNIQUE

Tudor Dachin, Dan Pitica, Gabriel Chindris

[PP. 201-204.:](#)

AN INNOVATIVE APPROACH TOWARDS E-HEALTH IN DEVELOPMENT OF TELE AUSCULTATION SYSTEM FOR HEART USING GSM MOBILE COMMUNICATION TECHNOLOGY

Muhammad Ahmed Khan, Syed Faraz Jawed, Muhammad Owais Khan, Osama Mazhar

[PP. 205-210.:](#)

A NEW LOW STRESSES HIGH-EFFICIENCY STEP-DOWN CONVERTER

Septimiu Lica, Aurel Cireşan, Cristina Băbăiță, Dan Lascu

[PP. 211-214.:](#)

MULTIFUNCTIONAL COMMUNICATION SYSTEM CONTROLLER IMPLEMENTED IN FPGA

C. Lung, A. Buchman

[PP. 215-218.:](#)

EMBEDDING ANDROID DEVICES IN AUTOMATION SYSTEMS

Maximilian Nicolae, Laurentiu Lucaci, Iona Moise

[PP. 219-222.:](#)

AUTOMATED SYSTEM FOR EVALUATING HEALTH STATUS

I. Orha, S. Oniga

[PP. 223-226.:](#)

SIX CHANNEL AC/DC CURRENT DATA LOGGER USED IN INDUSTRIAL APPLICATION

S. Pop, V. Bande, D. Pitica

[PP. 227-230.:](#)

MICROCONTROLLER BASED HEALTH MONITORING SYSTEM

J. Sütő, S. Oniga, I. Orha

[PP. 231-235.:](#)

PROGRAMMABLE INTERFACE FOR A SIGNAL GENERATOR AND LOGIC ANALYZER SYSTEM

Roland Szabó, Aurel Gontean

[PP. 237-240.:](#)

ELECTRONIC BALLAST IN HALF-BRIDGE CONFIGURATION WITH POWER FACTOR CORRECTION

Adrian Tăut, Ovidiu Pop, Alin Grama, Cristian Fărcaş

[PP. 241-244.:](#)

ELECTRO-MAGNETIC ACTUATED VIBRATING PLATFORM

[PP. 245-248.:](#)

EDLC HYBRID SYSTEM WITH INCREASED LIFESPAN FOR SUPPLYING AN UPS

Alexandru Vasile, Cristina Marghescu

**TOPIC H – APPLIED RELIABILITY**

[PP. 251-254.:](#)

ON CHANGE DETECTION FOR IMPROVED RELIABILITY

Dorel Aiordachioaie, Mihaela Andrei

[PP. 255-258.:](#)

LEAD/LEAD FREE SOLDER JOINTS COMPARATIVE ELECTRICAL TESTS AS FUNCTION OF MICROSTRUCTURE AND SOLDERING THERMAL PROFILE

M. Branzei, F. Miculescu, A. Bibis, I. Cristea, I. Plotog, G. Varzaru, B. Mihailescu

[PP. 259-262.:](#)

INVESTIGATING THE MECHANICAL EFFECT OF THE SOLDER JOINT THICKNESS WITH SIMULATION

Tamás Garami, Olivér Krammer

[PP. 263-266.:](#)

MONITORING OF METALIZED FILM CAPACITORS DEGRADATION WITH IMPEDANCE NONLINEARITY MEASUREMENT

Martin Plaček, Pavel Mach

[PP. 267-270.:](#)

ELECTROCHEMICAL MIGRATION OF COPPER IN PURE WATER USED IN PRINTED CIRCUIT BOARDS

Bálint Medgyes, Balázs Illés, Dániel Rigler, Miklós Ruzsinkó, László Gál

[PP. 271-276.:](#)

PSEUDO RANDOM SELF-TEST ARCHITECTURE FOR ADVANCED ENCRYPTION STANDARD

Flavius Opritoiu, Andreea Bozesan, Mircea Vladutiu

[PP. 277-282.:](#)

FACTORS INFLUENCING THE FORMATION OF VOIDS IN CHIP COMPONENT SOLDER JOINTS

Mihaela Pantazică, Paul Svasta, Heinz Wohlrabe, Klaus-Jürgen Wolter

[PP. 283-286.:](#)

LEAD/LEAD FREE SOLDER JOINTS COMPARATIVE SHEAR TESTS FUNCTION OF WORKING TEMPERATURE AND SOLDERING THERMAL PROFILE

Ioan Plotog, Gaudentiu Varzaru, Bogdan Mihailescu, Mihai Branzei, Adrian Bibis, Ionut Cristea

**TOPIC I – CHALLENGE IN GLOBAL EDUCATION**

[PP. 289-293:](#)

NEW FRONTIERS IN EDUCATION - TRAINING IN BIOLOGY FOR ELECTRICAL ENGINEERS

Melinda Varga, Klaus-Jürgen Wolter